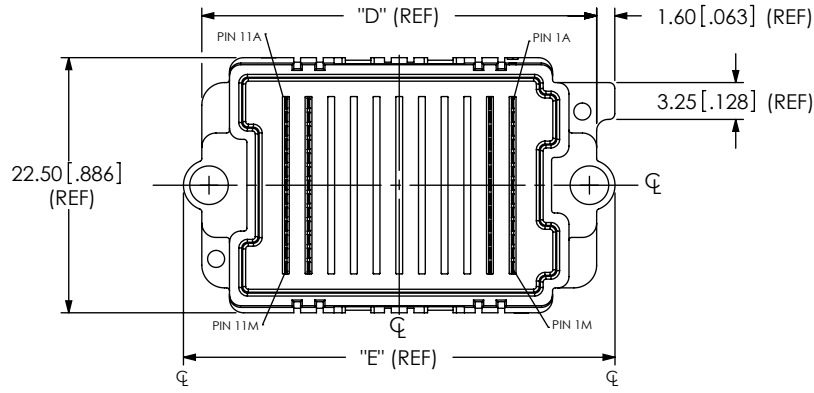


DESIGNED & DIMENSIONED IN MILLIMETERS  
(INCHES FOR REFERENCE ONLY)

HDAM-XX-XX.X-X-13-X-XX

DO NOT SCALE FROM THIS PRINT



No OF POSITIONS  
(13 ROW PER POSITION)  
-11  
-15  
-23

LEAD STYLE  
-12.0: 12MM  
-17.0: 17MM

OPTION  
-P: PICK & PLACE PAD  
(USE MPP-26-01-N)  
-TR: TAPE & REEL  
(ONLY TOOLED FOR HDAM-23-12.0-X-13-X)

SOLDER CHARGE MATERIAL  
-1: 63%TIN / 37% LEAD  
-2: 95.5% TIN / 3.8% SILVER  
0.7% COPPER (LEAD FREE)

PLATING SPECIFICATION  
-S: 30 μ" SELECTIVE GOLD IN MATING AREA,  
MATTE TIN ON TAIL AND GUIDE PINS

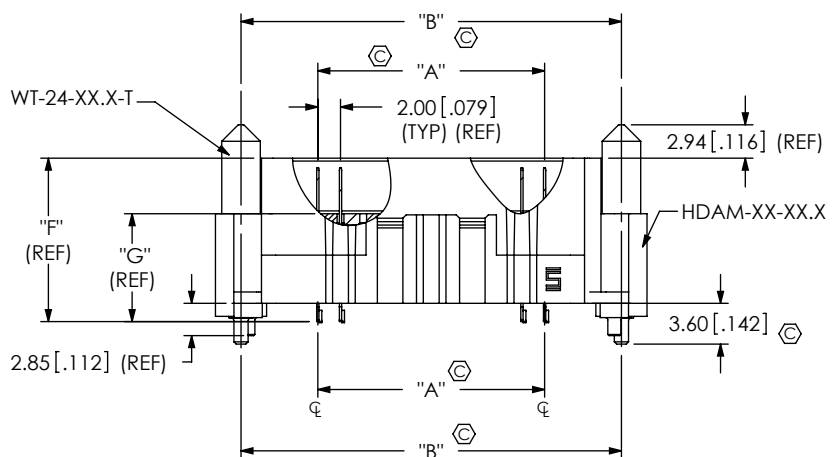
No OF ROWS  
-13

**TABLE 1**

STYLE	"BODY CALLOUT"	"TERMINAL WAFER"	"GUIDE PIN"
-12.0	HDAM-XX-12.0	SUB-IM-T-1M35-12.0-S-X	WT-24-12.0-T
-17.0	HDAM-XX-17.0	SUB-IM-T-1M35-17.0-S-X	WT-24-17.0-T

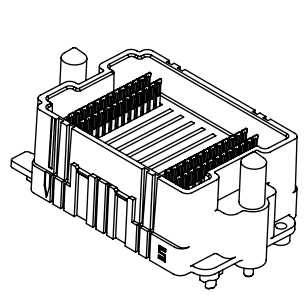
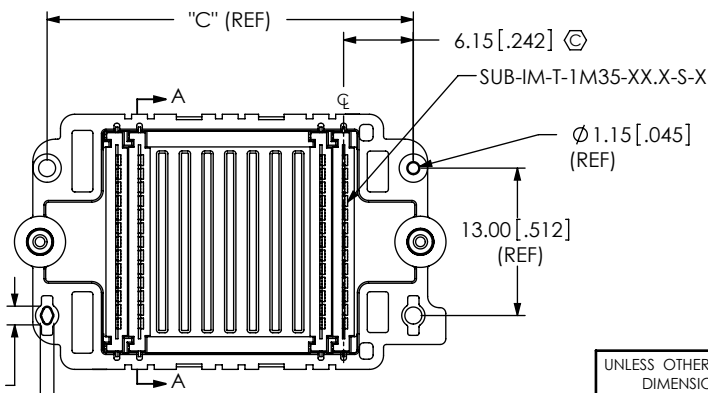
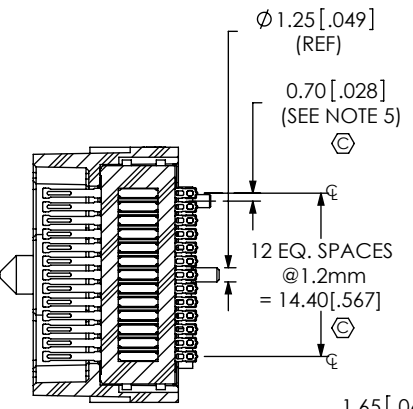
**TABLE 2**  
STACK HEIGHT

HDAM LEAD STYLE	HDAF LEAD STYLE	
	-08.0	-18.0
-12.0	20.0MM	30.0MM
-17.0	25.0MM	35.0MM

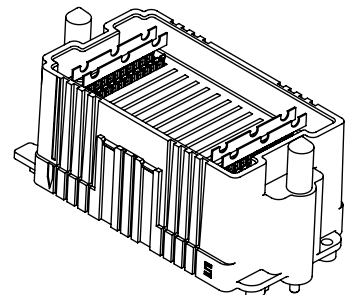


**TABLE 3**

No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	12	20.0 [0.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	14.41 [0.567]	9.51 [0.374]
15	12	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	14.41 [0.567]	9.51 [0.374]
23	12	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.493]	14.41 [0.567]	9.51 [0.374]
11	17	20.0 [0.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	19.41 [0.764]	14.51 [0.571]
15	17	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	19.41 [0.764]	14.51 [0.571]
23	17	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.443]	19.41 [0.764]	14.51 [0.571]



(-12.0 SHOWN)



(-17.0 SHOWN)

SECTION A-A

FIG 1  
-11: 11 POSITION  
(HDAM-11-12.0-X-13-X-X SHOWN)  
(SOME WAFERS NOT SHOWN FOR CLARITY)

NOTES:

1. Ⓢ REPRESENTS A CRITICAL DIMENSION.
2. MINIMUM PUSHOUT FORCE: 2.22N [0.5 LB]. FOR WAFERS
3. CONNECTORS TO BE PACKAGED IN TRAYS IF -TR OPTION IS NOT SELECTED.  
-TR OPTION IS ONLY TOOLED FOR HDAM-23-12.0-X-13-X.
4. USE THESE SURFACES TO MEASURE "G" DIMENSION.
5. DIMENSION FROM Ⓢ OF END TAIL TO Ⓢ OF -A PIN.

UNLESS OTHERWISE SPECIFIED,  
DIMENSIONS ARE IN  
MILLIMETERS [INCHES].  
TOLERANCES ARE:  
DECIMALS ANGLES  
.X: ±0.3 [0.1]  
.XX: ±0.13 [0.05]  
.XXX: ±0.051 [0.020]

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520 PARK EAST BLVD. NEW ALBANY, IN 47150  
PHONE: 812-944-6733 FAX: 812-948-5047  
e-Mail: info@SAMTEC.com code 55322

MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 1:5:1

INSULATOR: LCP. COLOR: BLACK  
CONTACT: COPPER ALLOY  
WAFAER MATERIAL: LCP. COLOR: BLACK  
GUIDE PIN MATERIAL: BRASS  
PICK AND PLACE PAD: COPPER ALLOY

DESCRIPTION:  
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.  
**HDAM-XX-XX.X-X-13-X-XX**

BY: D KNOWLDEN 7/15/2005 SHEET 1 OF 3

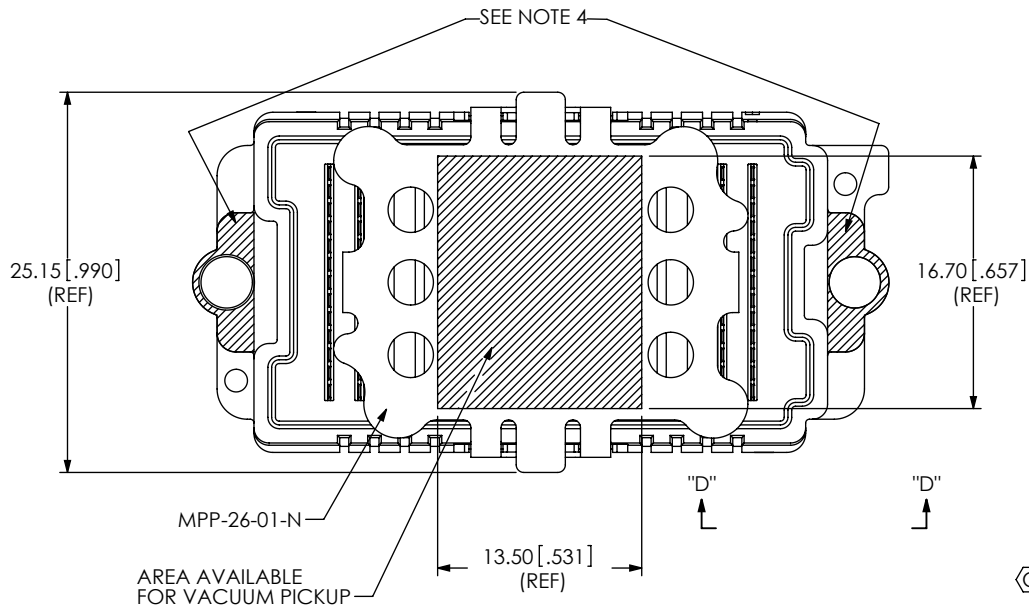
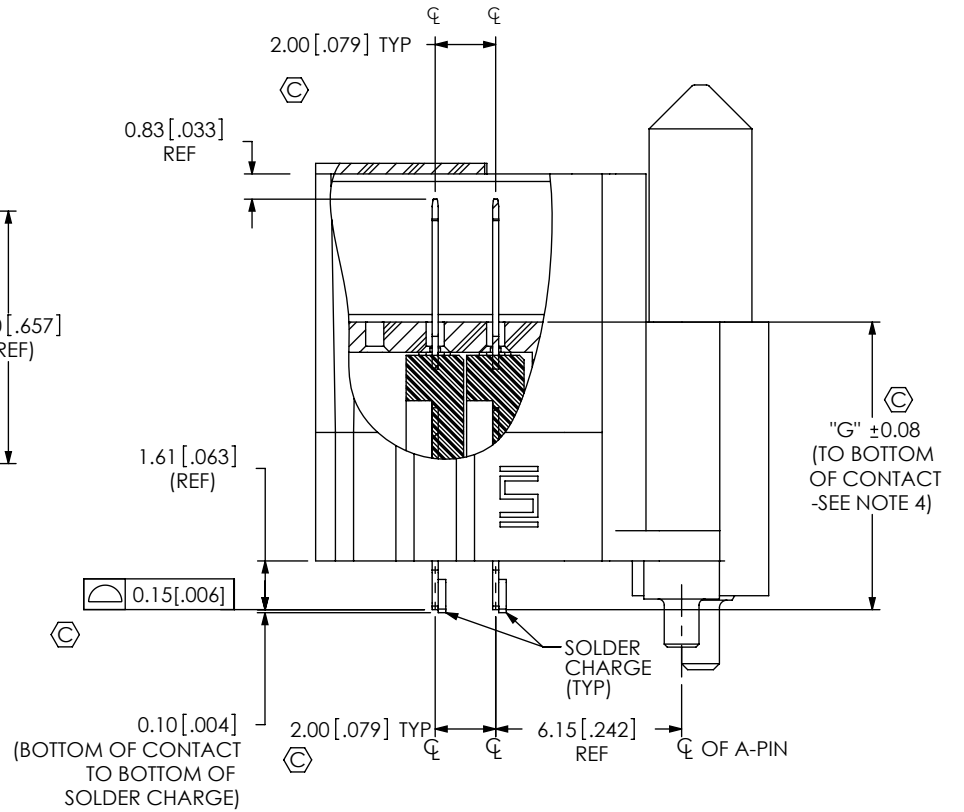
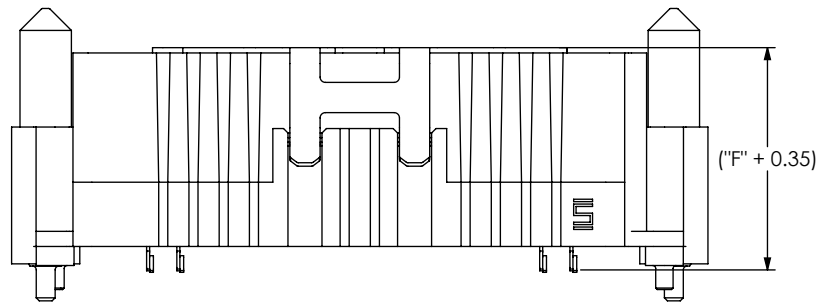


FIG 2  
-15: 15 POSITION  
(HDAM-15-12.0-X-13-X-P SHOWN)  
(SOME WAFERS NOT SHOWN FOR CLARITY)



VIEW D-D  
SCALE 4:1

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DO NOT SCALE DRAWING

SHEET SCALE: 2:1

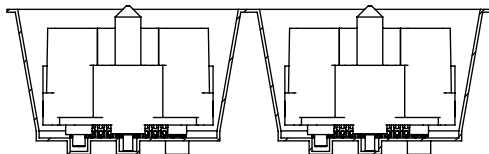
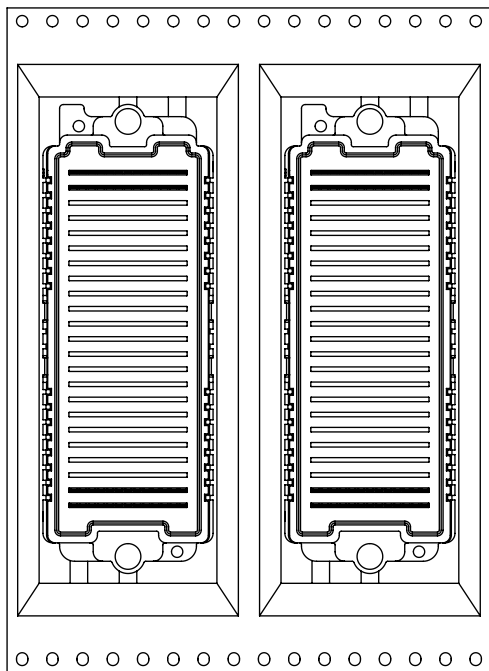
**samtec**

520 PARK EAST BLVD, NEW ALBANY, IN 47150  
PHONE: 812-944-6733 FAX: 812-948-5047  
e-Mail: info@SAMTEC.com code 55322

DESCRIPTION:  
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY


DWG. NO.  
**HDAM-XX-XX.X-X-13-X-XX**

BY: D KNOWLDEN 7/15/2005 SHEET 2 OF 3



USER DIRECTION OF UNREELING →  
POCKET NOT DETAILED

-TR PACKAGING VIEW  
(ONLY TOOLED FOR HDAM-23-12.0-X-13-X)

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	<p>520 PARK EAST BLVD, NEW ALBANY, IN 47150 PHONE: 812-944-6733 FAX: 812-948-5047 e-Mail info@SAMTEC.com code 55322</p>
	<p>DESCRIPTION: 2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY</p>
	<p>DWG. NO. <b>HDAM-XX-XX.X-X-13-X-XX</b></p>
<p>BY: D KNOWLDEN 7/15/2005 SHEET 3 OF 3</p>	